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LIGHTOP TECHNOLOGY CO., LTD.

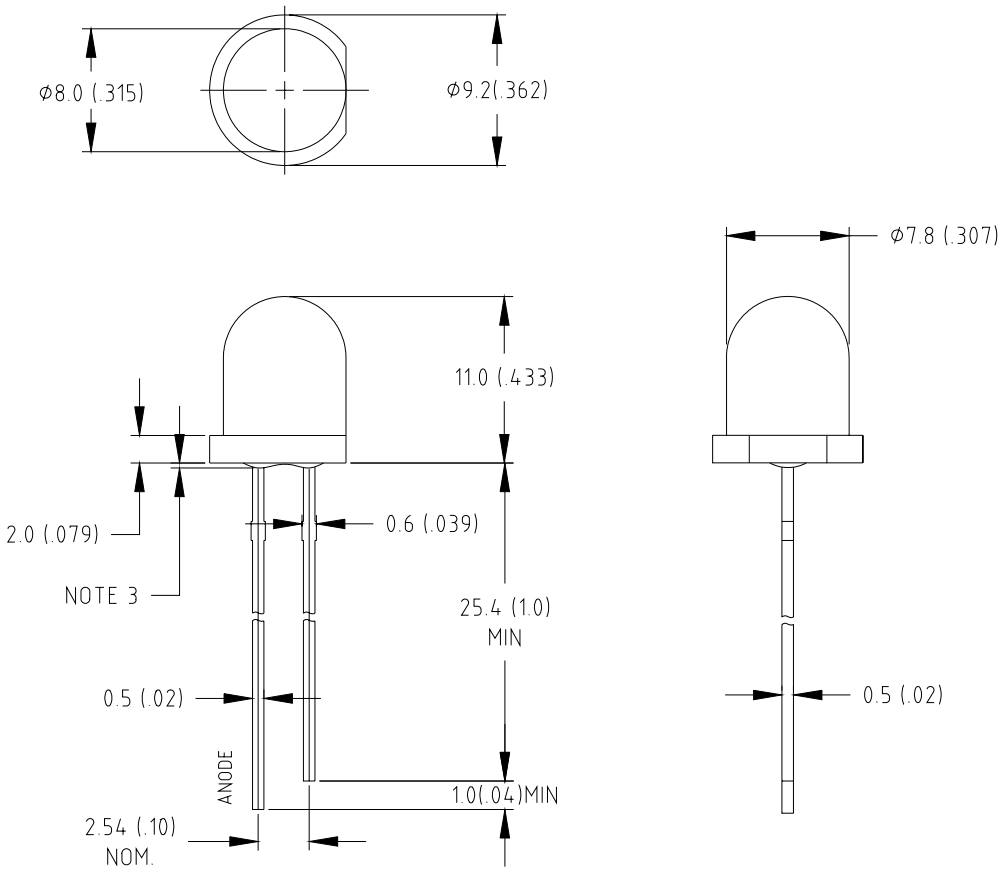
Data Sheet

REVISION	01
ISSUE DATE	2012/08/16
APPROVAL BY	JASON
PREPARED BY	LUOFAXING

Features:

1. Low power consumption
2. High efficiency
3. Reliable and rugged
4. Chip Material: GaP
5. Lens Color: Green Diffused
6. Source Color: Yellowish GREEN

Outline Dimensions:



Note：

1. All dimensions are in millimeters (inches)
2. Tolerance is ±0.25mm (0.01”) unless otherwise noted
3. Specifications are subject to change without notices.

Absolute Maximum Ratings at Ta=25℃:

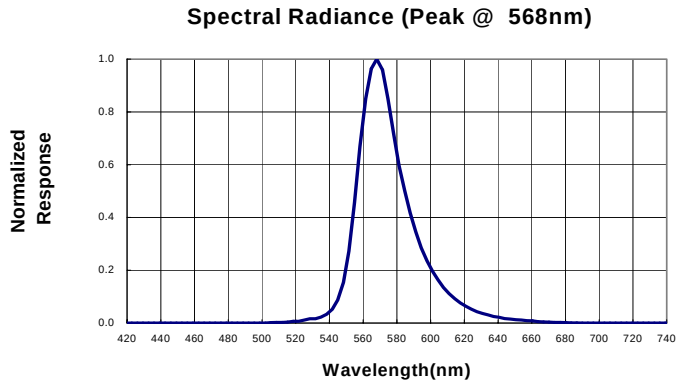
Parameter	Maximum	Unit
Power Dissipation	130	mW
Peak Forward Current (1/10 Duty Cycle,0.1ms Pulse Width)	100	mA
Continuous Forward Current	50	mA
Derating Linear From 50℃	0.4	mA/℃
Reverse Voltage	5	V
Operating Temperature Range	-30℃ to + 80℃	
Storage Temperature Range	-40℃ to + 100℃	
Lead Soldering Temperature [1.6mm(0.63”) from body]	255℃ for 5 Seconds	

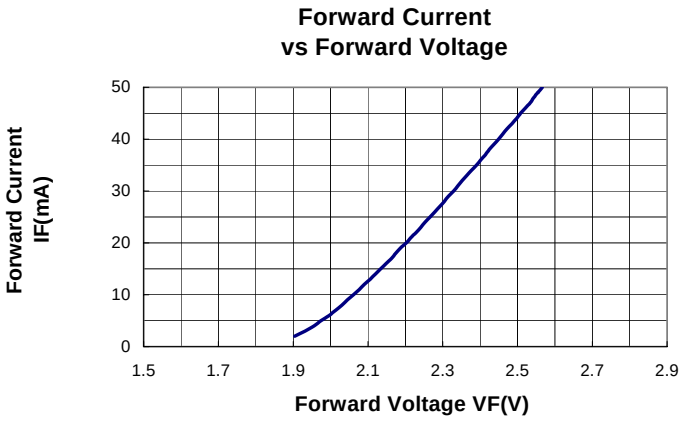
Electrical/Optical Characteristics at Ta=25℃:

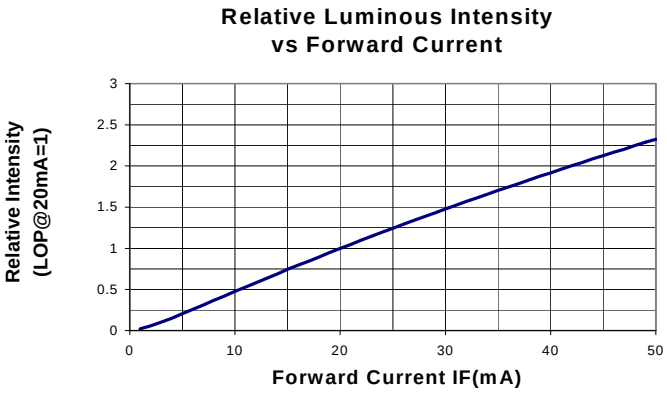
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	Iv	I_F=20mA	28	45		mcd
Dominant Wavelength	λd	I_F=20mA	565	570	575	nm
Viewing Angle	2θ 1/2	I_F=20mA		50		deg
Forward Voltage	V_F	I_F=20mA	1.8	2.2	2.6	V
Reverse Current	I_R	V_R=5V			10	uA

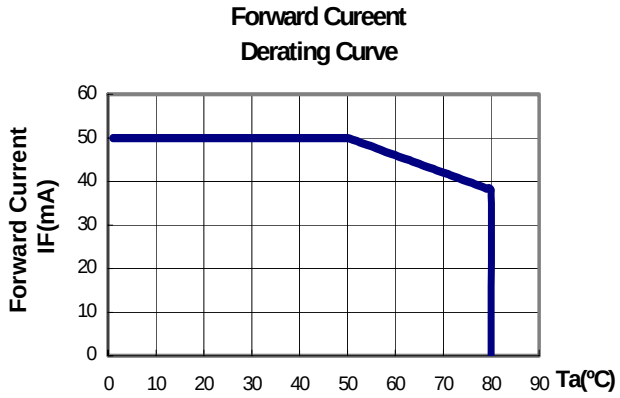
Typical Electrical/Optical Characteristics Curve:

(25℃ Ambient Temperature Unless Otherwise Noted)

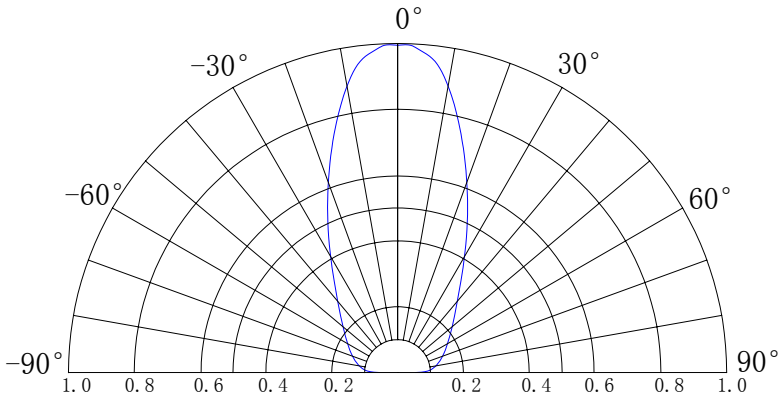






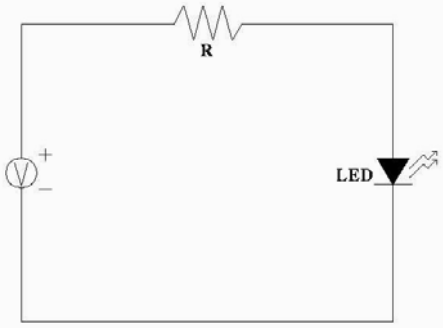


Beam Pattern



Relative Intensity (LOP @ MAX=1)

● Test Circuit



Reliability Test Standard

NO	Test Item	Test state	Test Conditions	Test Hours/Cycle	Sample /Size	Ac/Re
1	Solder Heat	Motionless state	TEMP:260℃±5℃	10SEC	40PCS	0/1
2	DC Operating Life	Development	TEMP:23±5℃ IF=20mA	1000HRS	40PCS	0/1
3	High Temperature Storage	Motionless state	TEMP:105℃	1000HRS	40PCS	0/1
4	Low Temperature Storage	Motionless state	TEMP:-45℃	1000HRS	40PCS	0/1
5	High Temperature High Humidity	Development	Ta= 65±5°C RH=90 ～ 95%	240H±2H	40PCS	0/1
6	Temperature Cycle	Development	H:+65℃ 95% 1H∫10MIN L:-25℃ 1H	40CYCLES	40PCS	0/1
7	Thermal Shock	Motionless state	H:+105℃ 30min ∫3MIN L:-45℃ 30min	20CYCLES	40PCS	0/1